High Voltage LED Series Chip on Board

LC016D-Gen.2

High efficacy COB LED package well-suited for use in spotlight applications

Features & Benefits

- Chip on Board (COB) solution makes it easy to design in •
- Simple assembly reduces manufacturing cost •
- Low thermal resistance •
- InGaN/GaN MQW LED with long time reliability •

Applications

- Spotlight / Downlight •
- LED Retrofit Bulbs
- Outdoor Illumination •





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1. Characteristics

a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +105	٥C	-
Storage Temperature	T _{stg}	-40 ~ +120	٥C	-
LED Junction Temperature	TJ	150	٥C	-
Case Temperature	Тс	115	٥C	
Forward Current	l _F	1150	mA	-
Power Dissipation	P _D	43.1	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics $(I_F = 450 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C})$

ltem	Unit	Rank	Min.	Тур.	Max.
Forward Voltage (V _F)	V	YZ	31.8	34.6	37.5
		3	70	-	-
Color Rendering Index (R_a)	-	5	80	-	-
		7	90		
Thermal Resistance (junction to case point)	°C/W		-	0.67	-
Beam Angle	0		-	115	-
Nominal Power	W			15.6	

Notes:

1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature ($T_J = T_C = T_a = 85 \text{ °C}$)

2) Samsungmaintains measurement tolerance of: forward voltage = ± 5 %, CRI = ± 1

3) Refer to the derating curve, '3. Typical Characteristics Graph'designed within the range.

c) Luminous Flux Characteristics (I_F = 450 mA)

CRI (R _a)	Nominal	Flux		Flux@Tc = 85 °C (lm)			
Min.	CCT (K)	Rank	Min.	Тур.	Max.		
	3000	D2	2486	2617	-		
70	4000	D2	2566	2701	-		
	5000	D2	2605	2742	-		
	2700	D2	2179	2293	-		
	3000	D2	2302	2423	-		
	3500	D2	2387	2513	-		
80	4000	D2	2430	2558	-		
	5000	D2	2452	2581	-		
	5700	D2	2452	2581	-		
	6500	D2	2430	2558	-		
	2700	D2	1868	1967	-		
	3000	D2	1980	2084	-		
90	3500	D2	2038	2146	-		
	4000	D2	2079	2189	-		
	5000	D2	2098	2209	-		

Notes:

- 1) The COB is tested in pulsed operating condition at rated test current (10 ms pulse width) and rated temperature $(T_J = T_C = 85 \text{ °C}).$
- 2) Samsungmaintains measurement tolerance of: Luminous flux = \pm 7 %, CRI = \pm 1

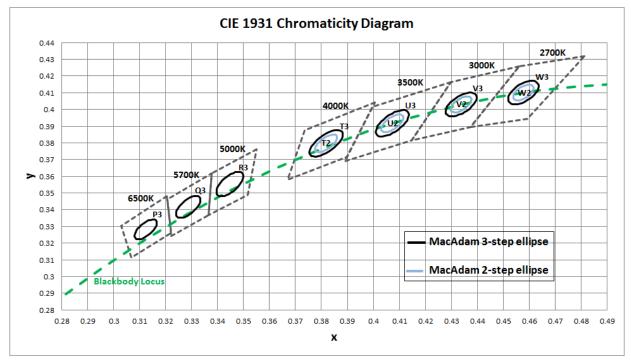
2. Product Code Information

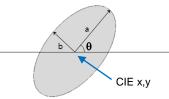
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S																	

Digit	PKG Information	Code	Specification
1 2 3	Samsung Package High Power	SPH	
4 5	Color	WН	White
6	Product Version	А	
7 8	Form Factor	HD	СОВ
9	Lens Type	N	No lens
10	Wattage or Model	E	LC016D
11	Internal Code	2	
		3	Min. 70 (85°C)
12	CRI & Sorting Temperature	5	Min. 80 (85°C)
		7	Min. 90 (85°C)
13 14	Forward Voltage (V)	ΥZ	31.8~37.5
		w	2700K
		v	3000K
		U	3500K
15	CCT (K)	т	4000K
		R	5000K
		Q	5700K
		Р	6500K
16	MacAdam Step	2	MacAdam 2-step
		3	MacAdam 3-step
17 18	Luminous Flux (Lm)	D2	COB D-series Gen.2 level

a) Binning Structure ($I_F = 450 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

CRI(R₂) Min.	Nominal CCT(K)	Product Code	V _F Rank	Color Rank	Flux Rank	Flux Range (Φ _v , lm)
	3000	SPHWHAHDNE23YZV3D2	ΥZ	V3	D2	2486 ~
70	4000	SPHWHAHDNE23YZT3D2	ΥZ	Т3	D2	2566 ~
	5000	SPHWHAHDNE23YZR3D2	ΥZ	R3	D2	2605 ~
		SPHWHAHDNE25YZW2D2		W2	P.c	
	2700	SPHWHAHDNE25YZW3D2	YZ	W3	D2	2179 ~
		SPHWHAHDNE25YZV2D2	\/ 7	V2	20	
	3000	SPHWHAHDNE25YZV3D2	YZ	V3	D2	2302 ~
		SPHWHAHDNE25YZU2D2	YZ	U2		2207
80	3500	SPHWHAHDNE25YZU3D2		U3	D2	2387 ~
		SPHWHAHDNE25YZT2D2	··· YZ	T2	_	
	4000	SPHWHAHDNE25YZT3D2		Т3	D2	2430 ~
	5000	SPHWHAHDNE25YZR3D2	ΥZ	R3	D2	2452 ~
	5700	SPHWHAHDNE25YZQ3D2	YZ	Q3	D2	2452 ~
	6500	SPHWHAHDNE25YZP3D2	ΥZ	P3	D2	2430 ~
	0700	SPHWHAHDNE27YZW2D2	\/ 7	W2	Do	1000
	2700	SPHWHAHDNE27YZW3D2	YZ	W3	D2	1868 ~
		SPHWHAHDNE27YZV2D2		V2	20	
	3000	SPHWHAHDNE27YZV3D2	YZ	V3	D2	1980 ~
90		SPHWHAHDNE27YZU2D2		U2	20	
	3500	SPHWHAHDNE27YZU3D2	YZ	U3	D2	2038 ~
		SPHWHAHDNE27YZT2D2		T2	20	
	4000	SPHWHAHDNE27YZT3D2	YZ	Т3	D2	2079 ~
	5000	SPHWHAHDNE27YZR3D2	YZ	R3	D2	2098 ~





MacAdam Ellipse (W2, W3)									
Step	CIE x	CIE y							
2-step	0.4578	0.4101	53.70	0.0054	0.0028				
3-step	0.4578	0.4101	53.70	0.0081	0.0042				

MacAdam Ellipse (U2, U3)								
Step	CIE x	CIE y						
2-step	0.4073	0.3917	54.00	0.0062	0.0028			
3-step	0.4073	0.3917	54.00	0.0093	0.0041			

MacAdam Ellipse (R3)									
Step	Step CIE x CIE y θ a b								
3-step 0.3447 0.3553 59.62 0.0082 0.0035									

MacAdam Ellipse (P3)									
Step CIE x CIE y θ a b									
3-step	0.3123	0.3282	58.5700	0.0067	0.0029				

MacAdam Ellipse (V2, V3) Step CIE x CIE y θ a b 2-step 0.4338 0.403 53.22 0.0056 0.0027 3-step 0.4338 0.4030 53.22 0.0083 0.0041

	MacAdam Ellipse (T2, T3)								
Step	CIE x	CIE y							
2-step	0.3818	0.3797	53.72	0.0063	0.0027				
3-step	0.3818	0.3797	53.72	0.0094	0.0040				

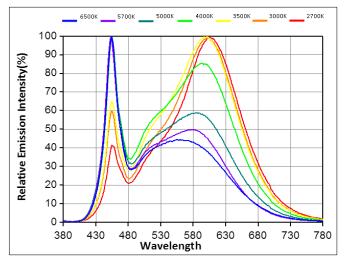
MacAdam Ellipse (Q3)						
Step	CIE x	CIE y			b	
3-step	0.3287	0.3417	59.0950	0.0075	0.0032	

Note:

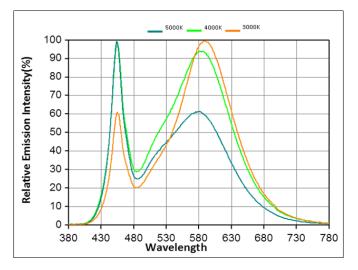
Samsung maintains measurement tolerance of: $Cx, Cy = \pm 0.005$

3. Typical Characteristics Graphs

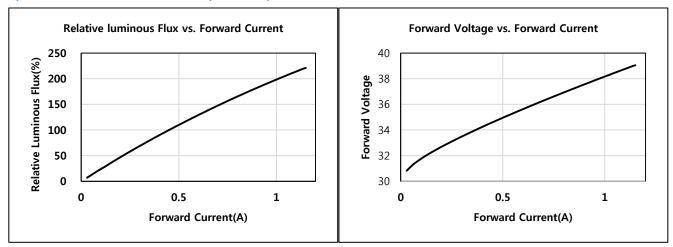
a) Spectrum Distribution (I_F = 450mA, T_J = 85 °C) CRI Ra 80+



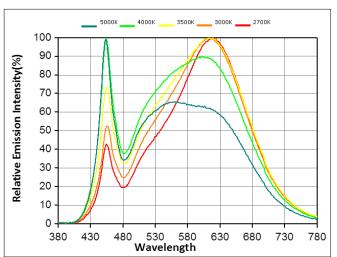
CRI Ra 70+



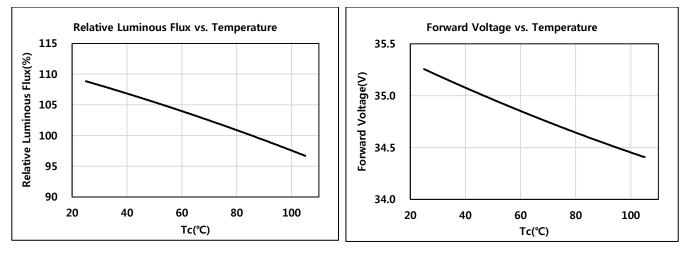
b)Forward Current Characteristics (T_J = 85 °C)



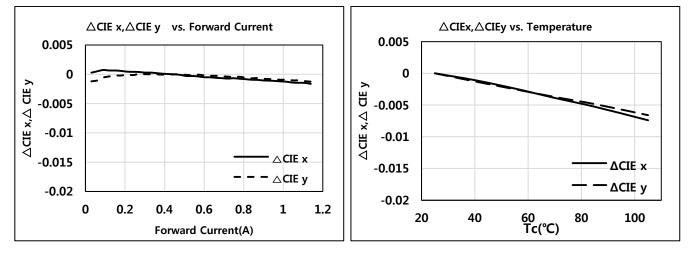
CRI Ra 90+



c) Temperature Characteristics(I_F = 450mA)

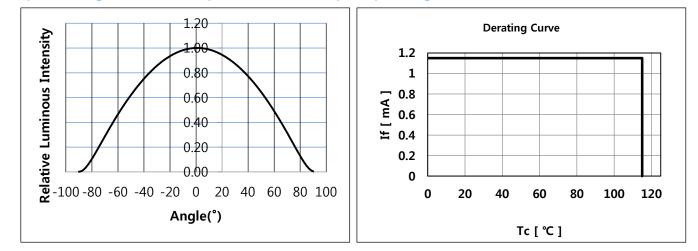


d) Color Shift Characteristics (T_J = 85 °C,I_F =450mA, CRI = 80+)

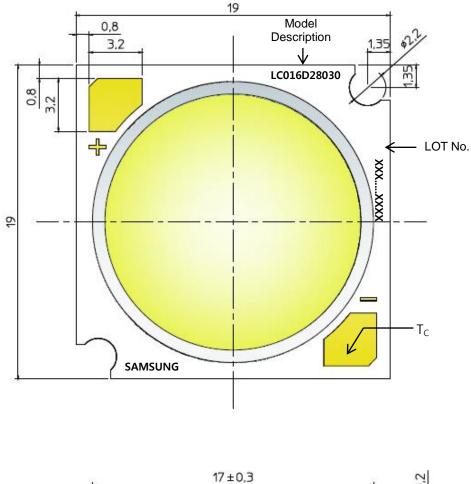


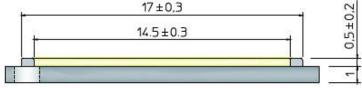
e) Beam Angle Characteristics ($I_F = 450 \text{ mA}, T_J = 85 \text{ }^{\circ}\text{C}$)

f) Derating Characteristics



4. Outline Drawing & Dimension







ltem	Dimension	Tolerance	Unit
Length	19.0	±0.30	mm
Width	19.0	±0.30	mm
Height	1.50	±0.20	mm
Light Emitting Surface (LES) Diameter	14.5	±0.30	mm

Note: Denoted product information above is only an example (LC016D28030 : LC016D, Gen2, CRI80+, 3000K)

5. Reliability Test Items & Conditions

a) Test Items

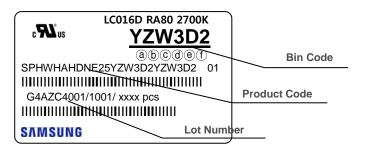
Test Item	Test Condition	Test Hour / Cycle	
High Temperature Humidity Life Test	60 °C, 90 % RH,, DC Derating, $\rm I_F$	1000 h	
High Temperature Life Test	85 °C, DC Derating, I _F	1000 h	
Low Temperature Life Test	-40 °C, DC, Derating I _F	1000 h	
High Temperature Storage	120 °C	1000 h	
Low Temperature Storage	-40 °C	1000 h	
Temperature Humidity Storage	60 °C, 90% RH	1000h	
TemperatureCycle On/Off Test	-40 °C/ 85 °C each 20 min, 30 min transfer power on/off each 5 min, DC Derating, $I_{\rm F}$ = max	100 cycles	
ESD (HBM)	R ₁ : 10 MΩ R ₂ : 1.5 kΩ C: 100 pF	5 times	
ESD (MM)	R ₁ : 10 MΩ R ₂ : 0 kΩ C: 200 pF	5 times	
Vibration Test	20~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔max. frequency 4 min transfer	4 times	
Mechanical Shock Test	1500g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times	
Sulfur Resistance	25 °C, 75%, H2S 15 ppm	504h	

b) Criteria for Judging the Damage

ltem	Symbol	Test Condition	Limit	
	Symbol	(T _c = 25 °C)	Min.	Max.
Forward Voltage	V _F	I _F = 450 mA	L.S.L. * 0.9	U.S.L. * 1.1
Luminous Flux	Φν	I _F = 450 mA	L.S.L * 0.7	U.S.L * 1.3

6. Label Structure

a) Label Structure



Note: Denoted bincode and product code above is only an example (see description on page 5)

Bin Code:

- (a)(b): Forward Voltagebin (refer to page11)
- ©d: Chromaticitybin (refer to page 9-10)
- (e) f): Luminous Fluxbin (refer to page 6)

b) Lot Number

The lot number is composed of the following characters:

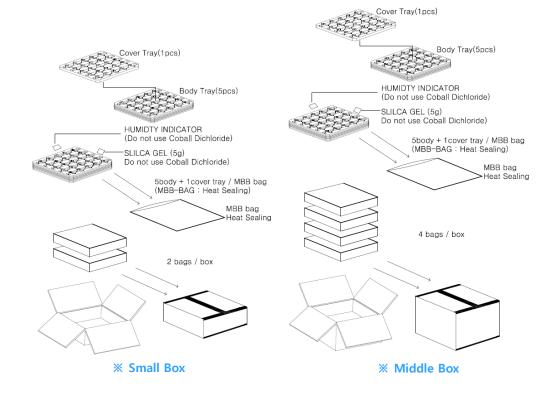


- 1 3456789 / 1abc / xxxx pcs
- 1 : Production site (S: Giheung, Korea, G: Tianjin, China)
- 2 : 4(LED)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (Z: 2015, A: 2016, B: 2017...)
- (5) : Month (1~9, A, B, C)
- 6789 : Day (1~9, A, B~V)
- (a)(b)(c) : Product serial number (001 ~ 999)

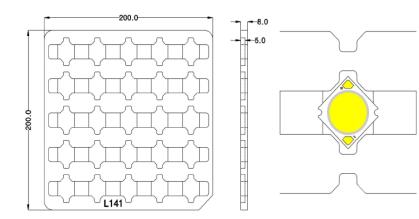
7. Packing Structure

	Max. quantity	Dimension(mm)			
Packing material	in pcs of COB	Length	Width	Height	Tolerance
Tray	25	200	200	8	1
Anti-Static Bag	125 (5 trays)	320	270	-	+/- 0.5
Outer Box (Small)	250 (2 bags)	225	225	65	5
Outer Box (Middle)	500 (4 bags)	225	225	130	5

a) Packing Structure

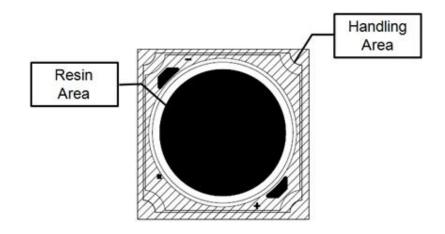


b) Tray



8. Precautions in Handling & Use

- This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
 b. Stored at <10 % RH
- 4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 5) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 6) Devices must be baked for 1 hour at 60 ± 5 °C, if baking is required.
- 7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- The thermal management is one of the most critical factors for the LED lighting system. Especially the LED junction temperature should not exceed the absolute maximum rating while operation of LED lighting system.
 For more information, please refer to Application Note 'Mechanical & Thermal Guide for COB'.
- 9) In case of driving LEDsaround the minimum current level (If_min), chips might exhibit different brightness due to the variation in I-V characteristics of each one. This is normal and does not adversely affect the performance of product.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.



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Samsung Electronics Co., Ltd. 95, Samsung 2-ro Giheung-gu Yongin-si, Gyeonggi-do, 446-711 KOREA

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